

# Lecture 12

## Agenda:

- Capacitive Interface Circuits

# Capacitive Sensing

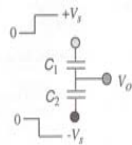
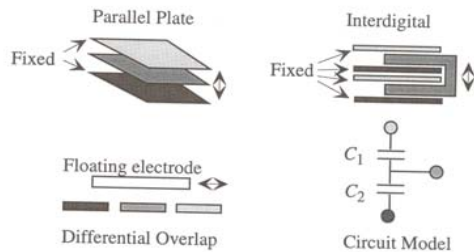
## Capacitive Sensing



### MEMS Capacitive Sensors:

- High impedance
- Small sensing capacitance
- Very small signal
- Parasitic capacitance
- Noise

# Capacitive Sensing



$$V_0 = -V_s + \frac{C_1}{C_1 + C_2} (2V_s) = \frac{C_1 - C_2}{C_1 + C_2} V_s$$

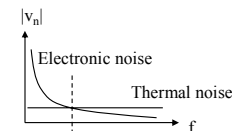
### Differential Capacitive Sensing

- First order cancellation of many effects
  - Temperature variations
- Common mode rejection

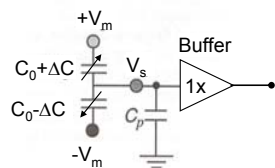
# Capacitive Sensing

## Challenges

- Small sensing capacitance
- High output impedance
- Parasitics
- Noises
  - 1/f noise
- Offset
- DC bias



## Parasitic Capacitance

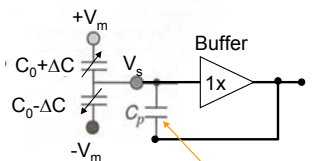


$$V_s = \frac{2\Delta C}{2C_0 + C_p} V_m$$

If  $C_0 = 100\text{fF}$ ,  $C_p = 200\text{fF}$ ,

**The signal will be attenuated by half**

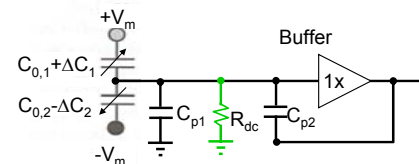
### Bootstrapping



Zero voltage across  $C_p$

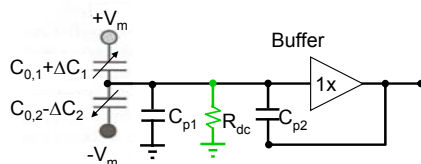
- Increased fabrication complexity
- Difficult to cancel all parasitics

## DC Bias at Sensing Node



- Charging on the small sensing capacitors causes drifting, instability and uncertain electrostatic force
- $R_{dc}$  provides DC bias, charging path
- Typical  $R_{dc} > 1\text{M}\Omega$

## DC Bias at Sensing Node



Typical  $R_{dc} > 1\text{M}\Omega$

- Polysilicon resistor:
  - Large silicon area
  - Large parasitics: capacitance; inductance
- Switched-capacitor circuits
- Diodes
- Sub-threshold transistors
- Long-channel transistors

## Capacitive Interface Circuits

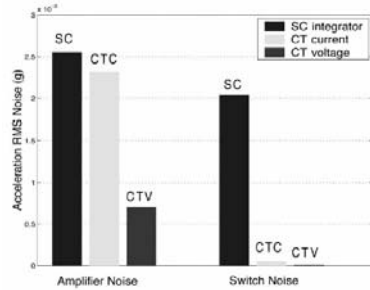
- ❑ Noise Analysis
- ❑ Input transistor optimization
- ❑ Chopper Stabilization (CHS)
  - Continuous-time amplifiers
- ❑ Correlated Double Sampling (CDS)
- ❑ CHS vs CDS Comparison
- ❑ Design Example

## Continuous-time (CT)

- **CT Voltage Sensing (CTV)**
  - Impedance-conversion buffer
  - Charge integration
- **CT Current Sensing (CTC)**
  - Transimpedance amplifier

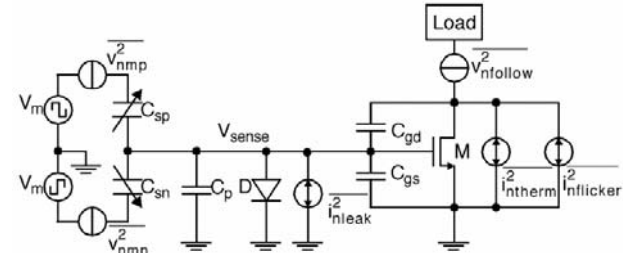
## Discrete-time (DT)

- **Switched Capacitor (SC) Sensing: Correlated Double Sampling (CDS)**



- Flicker noise
- Offset
- kT/C noise (CDS)
- Noise folding
- Charge injection
- Quantization noise

J. Wu et al., IEEE J. SSC, 2004



$$\begin{aligned} \frac{\overline{v_n^2}}{\Delta f}(f) &= \frac{\overline{v_{ntherm}^2}}{\Delta f}(f) + \frac{\overline{v_{nflicker}^2}}{\Delta f}(f) + \frac{\overline{v_{nleak}^2}}{\Delta f}(f) \\ &= \frac{K_f T}{W^\beta L^{\beta-1}} + \frac{K_f}{W L f} \\ &\quad + \frac{K_s I_{leak}}{(2C_s + C_p + C_{gs} + C_{gd})^2 f^2} \end{aligned}$$

J. Wu et al., IEEE J. SSC, 2004

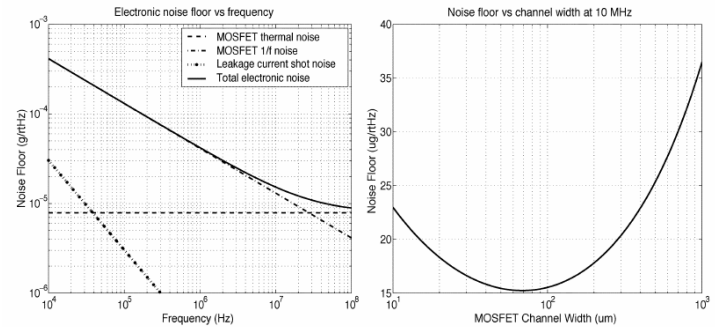
But, 
$$V_{sense} = \frac{2\Delta C}{2C_0 + C_p + C_{gs} + C_{gd}} V_m$$

and 
$$C_{gs} + C_{gd} = \left(\frac{2}{3}L + 2L_{overlap}\right)W$$

Increase W  $\Rightarrow$  Reduce 1/f noise and thermal noise  
But reduce sensitivity.

Maximize SNR given by 
$$\frac{V_{sense}^2}{\overline{v_n^2}}$$

$\Rightarrow$  Optimal input-transistor width



J. Wu et al., IEEE J. SSC, 2004

UNIVERSITY OF FLORIDA

## Chopper Stabilization

Modulation:  $V_s \times \text{Carrier signal } (f_M) \rightarrow V_{s1}$

Demodulation:  $V_{s2} \times \text{Carrier signal } (f_M) \rightarrow V_{s3}$

Low-pass Filter:  $V_{s3} \rightarrow V_{out}$

- Cancel amplifier offset and  $1/f$  noise

EEL6935 Advanced MEMS ©2005 H. Xie 13

UNIVERSITY OF FLORIDA

## Continuous-Time Amplifiers

### ■ Unity-gain Buffer With a Sub-threshold Biasing

- Use a feedback transistor operating at its subthreshold
- Bias voltage must be carefully set

EEL6935 Advanced MEMS ©2005 H. Xie 14

UNIVERSITY OF FLORIDA

## Continuous-Time Amplifiers

### ■ Unity-gain Buffer With a Sub-threshold Biasing

Luo, ISSCC 2003

- Noise floor: 110 nV/rHz
- Gain: 23 dB
- Switched-capacitor demodulator: Insensitive to dc offset

EEL6935 Advanced MEMS ©2005 H. Xie 15

UNIVERSITY OF FLORIDA

## Continuous-Time Amplifiers

### ■ Chopper Stabilization with Periodic Reset

modulator, switching bias, amplifier with dc/ac offset cancellation, demodulator, buffer & LFP

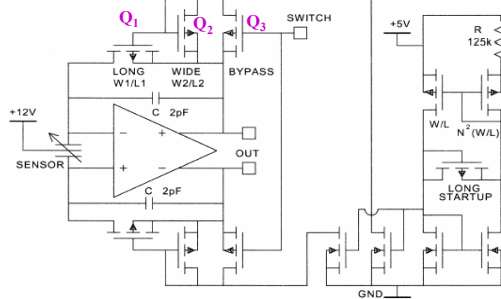
ac calibration, dc cancellation

- Chopper stabilization
- Optimal transistor sizing to minimize SNR
- DC offset cancellation
- Low-duty-cycle periodic reset for dc biasing
- Noise floor: ~50 nV/rHz

J. Wu et al., IEEE J. SSC, 2004

EEL6935 Advanced MEMS ©2005 H. Xie 16

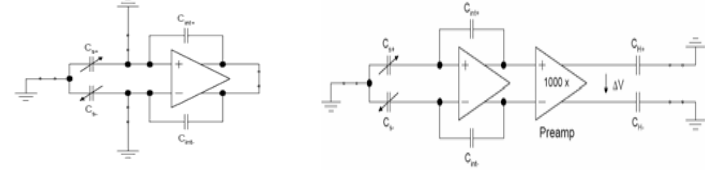
## ■ Transcapacitance Amplifier



- Bipolar input stage
- Controlled-impedance FET for biasing
- Q1 in triode-mode and Q2 saturated: 50MΩ
- Q3, 1/50 duty cycle: 2.5GΩ
- Temperature compensation: PTAT
- Noise floor: 12 zF/rtHz

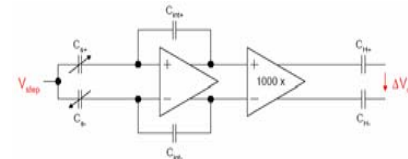
Geen et al., IEEE J. SSC, 2002

## ■ Correlated Double Sampling (CDS)



Step 1: Set DC level

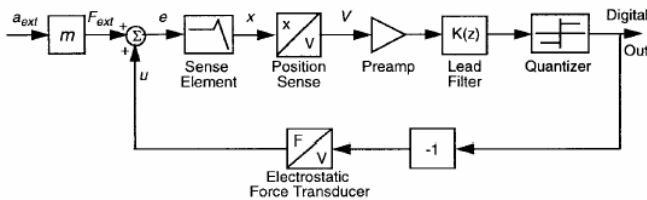
Step 2: Offset and 1/f noise cancellation



Step 3: Sensing  $\Delta C_s$

- Offset cancellation
- 1/f noise cancellation
- kT/C noise reduction
- but noise aliasing, switch noise still problematic
- Aliasing needed

Boser, Transducers 1997



- One-bit feedback
- Increased dynamic range
- Good linearity
- Digital output

- Higher cost
- Higher power consumption
- Not suitable for applications with high-g shock

Lemkin and Boser, IEEE J. SSC, 1999

Interface type	Advantages	Disadvantages
<b>Chopper-Stabilization</b>	<ul style="list-style-type: none"> <li>• Low noise: no aliasing, minimal number of noise sources</li> <li>• Low front-end power – SNR not limited by capacitor size</li> <li>• Suitable for discrete-component implementation</li> </ul>	<ul style="list-style-type: none"> <li>• Requires additional filtering and ADC for digital output</li> <li>• Requires large biasing resistors</li> </ul>
<b>Switch-Capacitor</b>	<ul style="list-style-type: none"> <li>• Robust DC biasing Good Linearity and accurate gain</li> <li>• Easy to integrate more functions (ADC, force-feedback)</li> <li>• Output can be digitized directly</li> <li>• No low-pass filter needed</li> </ul>	<ul style="list-style-type: none"> <li>• Higher noise – Noise folding, charge injection</li> <li>• Large capacitors needed for low kT/C noise</li> </ul>

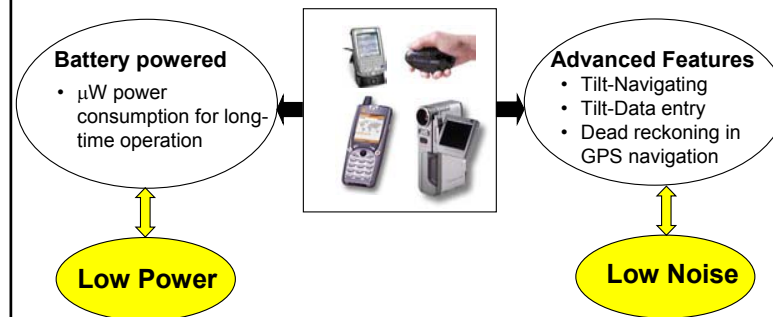
Other Groups: U-Mich, GA Tech, UF, ...

**Design Example:**

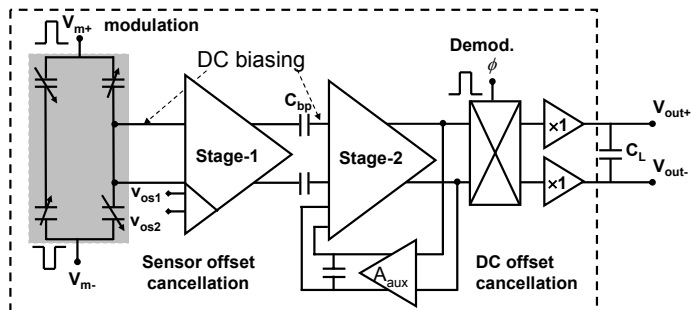
**Low-power low-noise interface circuit for accelerometers** (by D. Fang)

**Example: Low-power Low-noise Accelerometer**

- Low-Power and Low-Noise Operation are Critical in Emerging Applications



**Low-Power Low-Noise Architecture**



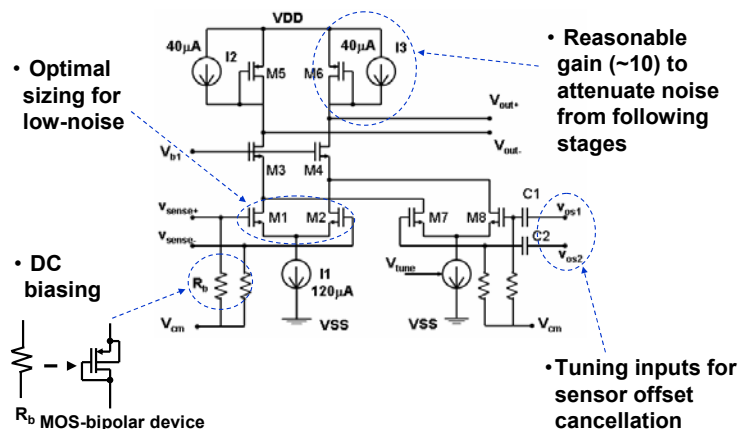
**Low Noise**

- Noise Matching
- High chopping frequency (0.1~2 MHz)

**Low Power**

- 2-stage, open-loop
- Stage-1 optimized for noise
- Stage-2 optimized for signal swing and linearity

**Interface Circuit Design: Stage-1**



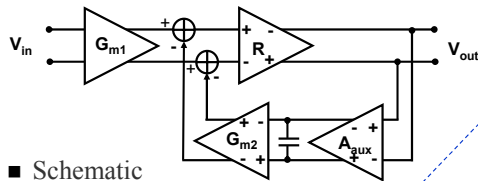
- Optimal sizing for low-noise

- DC biasing

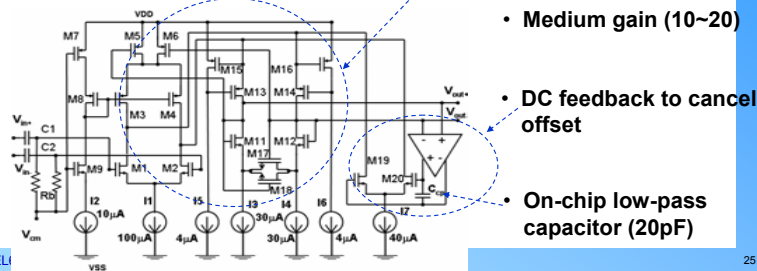
- Reasonable gain (~10) to attenuate noise from following stages

- Tuning inputs for sensor offset cancellation

### ■ Block Diagram

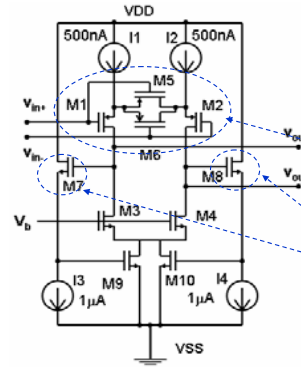


### ■ Schematic



- Folded-cascode with linearized trans-conductance load
- Optimized for linearity and signal swing
- Medium gain (10~20)
- DC feedback to cancel offset
- On-chip low-pass capacitor (20pF)

### ■ Used in DC feedback loop within stage-2



- Form a low-pass  $g_m$ -c filter ( $f_{cut-off}$  is about 50 kHz) with on-chip capacitor  $C_{cp}$
- Low sink current and source degeneration are used to get very low  $g_m$  (a few  $\mu A/V$ )
- M7 and M8 are used as level-shifter to keep common-mode level of outputs of the auxiliary amplifier in the right range

Chopping freq.	50 kHz ~ 1 MHz
Gain	40 dB
DC offset	<1 mV
Sensor offset attenuation	>26 dB
noise	24 $nV/\sqrt{Hz}$ , chopping at 1 MHz (simulation)
Power	330 $\mu A \times 3.3 V$

Fang and Xie, IASTED CSS 2004

- Boser, B.E., "Electronics for micromachined inertial sensors," TRANSDUCERS '97, pp.1169 – 1172.
- M. Lemkin and B. E. Boser, "A Three-Axis Micromachined Accelerometer with a CMOS Position-Sense Interface and Digital Offset-Trim Electronics," IEEE J. Solid-State Circuits, vol. SC-34, pp. 456-468, 1999
- Geen, J.A, Sherman, S.J, Chang, J.F, Lewis, S.R, "Single-chip surface micromachined integrated gyroscope with 50/spl deg/h Allan deviation", Micromachine Products Div., Analog Devices Inc., Cambridge, MA; Solid-State Circuits, IEEE Journal of, Publication Date: Dec 2002, pp.1860- 1866
- H. Kulah and K. Najafi, "A Low Noise Switched-Capacitor Interface Circuit for Sub-Micro Gravity Resolution Micromachined Accelerometers," European Solid-State Circuits Conference ESSCIRC02, pp 635-639, Florence, Italy, September 2002
- X. Jiang, S. A. Bhawe, J. I. Seeger, R. T. Howe, B. E. Boser, and J. Yasaitis, "SD Capacitive Interface for a Vertically Driven X&Y-Axis Rate Gyroscope," Proc. of the 28th European Solid-State Circuits Conference, Florence, Italy, Sept. 24-26, 2002, pp. 639-642.
- H. Kulah, J. Chae, N. Yazdi and K. Najafi, "A Multi-Step Electromechanical Sigma-Delta Converter for Micro-g Capacitive Accelerometers" International Solid-State Circuits Conference ISSCC 2003, pp. 202-203
- Luo, H.; Fedder, G.K.; Carley, L.R.; "A 1 mG lateral CMOS-MEMS accelerometer," MEMS 2000, pp. 502-507
- J. Wu, G.K. Fedder, L.R. Carley, "A low-noise low-offset chopper-stabilized capacitive-readout amplifier for CMOS MEMS accelerometers," The 2002 IEEE International Solid-State Circuits Conference (ISSCC 2002), pp.428-478
- B. Vakili Amini, S. Pourkamali, and F. Ayazi, "A 2.5V 14-bit Sigma-Delta CMOS-SOI Capacitive Accelerometer," in Tech. Dig. IEEE International Solid-State Circuits Conference (ISSCC 2004), pp. 314-315
- Fang, D., and Xie, H., "A Low-Power Low-Noise Capacitive Sensing Amplifier for Integrated CMOS-MEMS Inertial Sensors," The IASTED International Conference on Circuits, Signals and Systems (CSS'04), Clearwater Beach, FL.